

NOTE



All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters [and inches]. Unless otherwise specified, dimensions have a tolerance of ± 0.13 [$\pm .005$] and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of DIP programming switches (7000 and 7100 Series) for printed circuit (pc) board applications. 7000 Series switches are designed for a life of 7,000 cycles per pole. 7100 Series switches are recommended for programming applications where the number of cycles is limited to 2,000 per pole.

Switches are manually rocker actuated and are designed for wave soldering on printed circuit (pc) boards or insertion into DIP Sockets with in-row centerline spacing of 7.62 [.300]. 7000 series switches are black, and are available in 2 through 12 positions, while 7100 series switches are blue and available in 2 through 12 positions. Both series are available with a premium seal, an economy seal, or unsealed in the raised rocker (standard profile) or flush rocker profile (low profile). In addition, 7000 series switches are available with a side rocker profile (side actuated). Both series are individual single-pole, single-throw (SPST). 7000 series raised rocker profile switches may have ganged rockers for single-pole, double-throw (SPDT) and double-pole, double-throw (DPDT) make-before-break circuits.

The unsealed switches are designed for socket applications and the sealed switches are designed for soldering directly to the pc board. The sealants prevent flux and other contaminants from entering the switch during soldering and cleaning. The raised rocker and side rocker profiles come unsealed or with an optional economy or premium masking top seal. The flush rocker profile comes unsealed or with an optional economy tape top seal or premium masking top seal. The multi-pole switches come unsealed only. All switches come standard with a bottom seal. Switches are designed for use in logic level switching applications.

When corresponding with personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

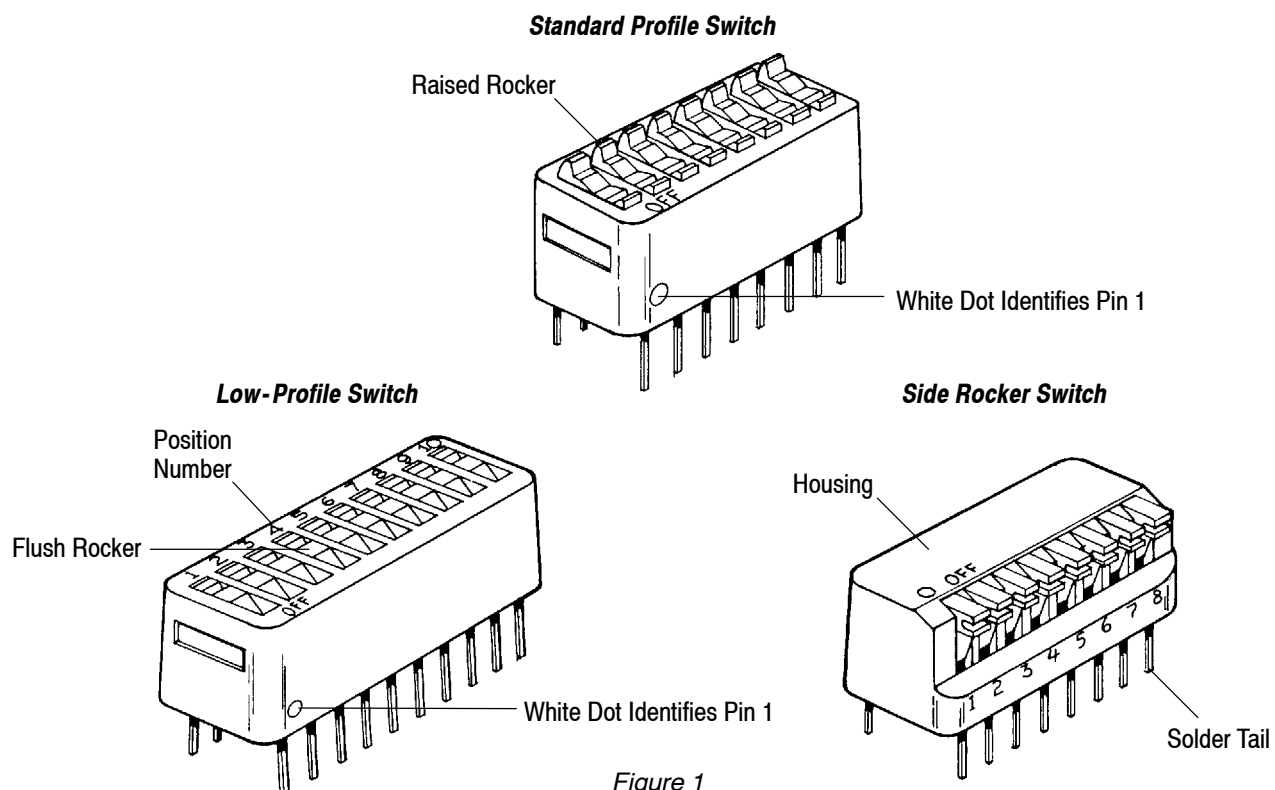


Figure 1

2. REFERENCE MATERIAL

2.1. Revision Summary

Revisions to this application specification include:

- Changed company logo

2.2. Customer Assistance

Reference Product Base Part Number 435802 and Product Code 4546 are representative of DIP programming switches (7000 and 7100 Series). Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product and tooling information. Such information can be obtained through a local Representative or, after purchase, by calling PRODUCT INFORMATION at the number at the bottom of page 1.

2.3. Drawings

Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the information contained in the Customer Drawings takes priority.

2.4. Specifications

Product Specifications 108-7519 (7000 series) and 108-7532 (7100 series) provide product performance and test information.

Qualification Test Reports 501-135 (7000 series) and 501-128 (7100 series) provide an independent corporate test report to show the switch conforms to the above mentioned Product Specifications.

2.5. Instructional Material

Instruction Sheets (408-series) provide product assembly instructions or tooling setup and operation procedures and Customer Manuals (409-series) provide machine setup and operating procedures. Documents available which pertain to this product are:

408-7779 Dual In-Line Package (DIP) Programming Switches (7000 and 7100 Series)

2.6. Manuals

Manual 402-40 can be used as a guide to soldering. This manual provides information on various flux types and characteristics with the commercial designation, flux removal procedures, and a guide for information on soldering problems.

3. REQUIREMENTS

3.1. Safety

Do not stack product shipping containers so high that the containers buckle or deform.

3.2. Limitations

The switches are designed to operate within a temperature range of -55° to 105°C [-67° to 221°F].

3.3. Storage

A. Ultraviolet Light

Prolonged exposure to ultraviolet light may deteriorate the chemical composition of components used in the switches.

B. Shelf Life

The switches should remain in the shipping containers until ready for use to prevent damage. These products should be used on a first in, first out basis to avoid storage contamination.

C. Chemical Exposure

Do not store switches near any chemicals listed below, as they may cause stress corrosion cracking in the components.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur Nitrites		Tartrates

NOTE

Where the above environmental conditions exist, phosphor-bronze contacts are recommended.



3.4. PC Board

A. Material and Thickness

The pc board material must be glass epoxy (FR-4 or G-10). The pc board thickness shall be 2.36 [.093].

NOTE

Contact *PRODUCT INFORMATION* at the number at the bottom of page 1 for suitability of other pc board materials and thicknesses.



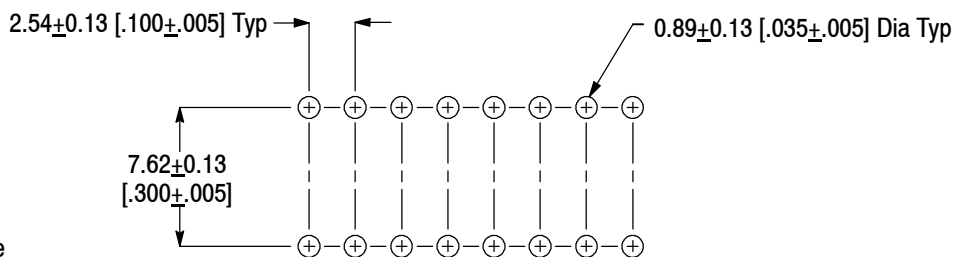
B. Tolerance

Maximum allowable bow of the pc board must be 0.08 [.003] over each 25.4 [1.00] of length.

C. Layout

The solder tail contact holes in the pc board must be precisely located to ensure proper placement and optimum performance of the switch. The layout dimensions and tolerances shown in Figure 2 must be observed when preparing pc boards for the various switches. The layout shows the top (component) side of the board.

Recommended PC Board Layout



Note: Not to Scale

Figure 2

3.5. Holes

The holes in the pc board for the contact solder tails must be drilled and plated through to specific dimensions given in Figure 3.

3.6. Mounting Requirements

Determine whether the switch will be soldered directly to the pc board (a sealed switch will be required), or whether the switch is to be installed in a socket (an unsealed switch can be used).

A. DIP Socket

1. Secure DIP socket to pc board according to instructions packaged with socket.
2. Start one row of contact leads into one row of contact cavities in socket, then rotate switch until it is parallel with socket.

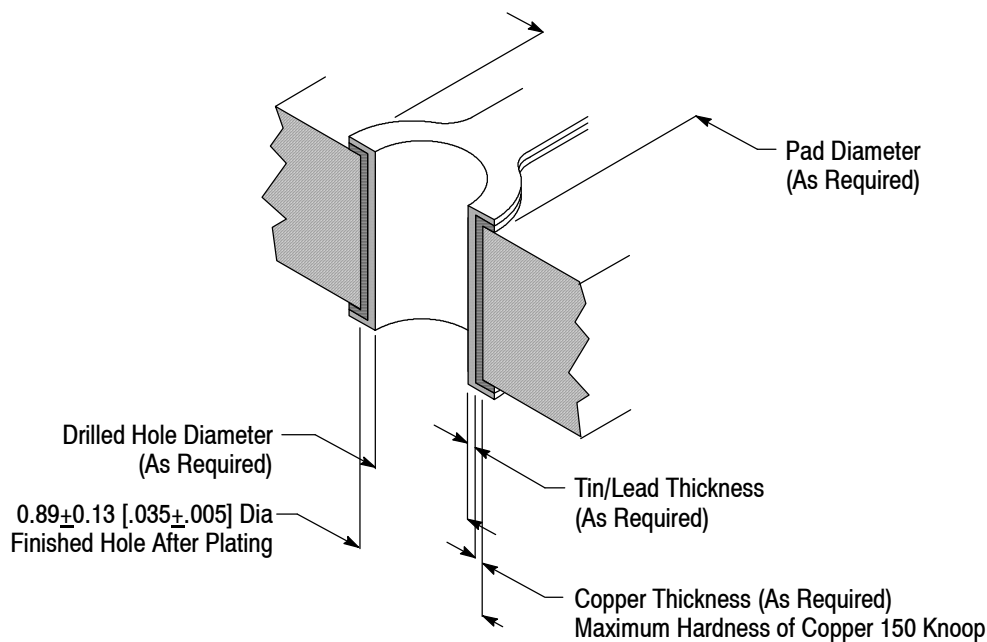


Figure 3

3. Gripping ends of switch push switch into socket until it is bottomed.
4. Determine which of the circuits are to be closed, then depress the applicable rockers to the ON position.
5. If installing a protective dust cover, check to be sure there are no obstructions on the switch rockers or in the protective cover, then slide the cover over the top of the housing.

B. PC Board

1. Make a layout on pc board according to dimensions shown in Figure 2.
2. Hold switch at a slight angle and start one row of contact leads into pc board holes. Do NOT over-insert. Switch should be rotated until second row of contact leads are aligned with opposite row of contact holes.
3. Make certain all contact leads have started entry into holes. Grip sides of switch and push switch into pc board until it is bottomed.
4. To hold switch in place during wave soldering, the four outside leads may be clinched inward at 45°. See Figure 4.

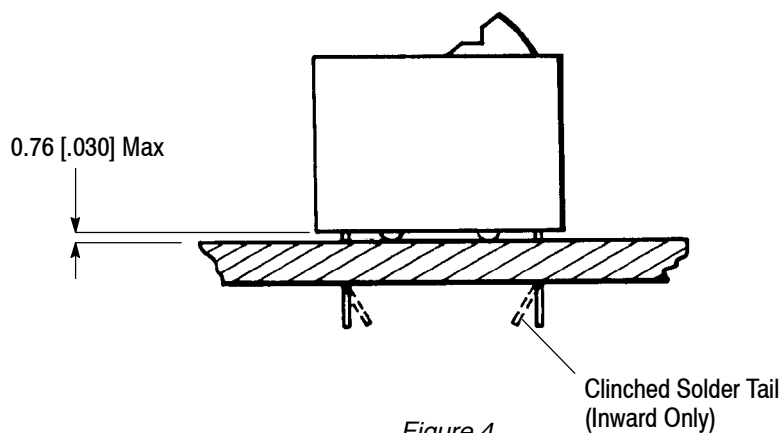


Figure 4

3.7. Soldering

A. Flux Selection

Solder tails must be fluxed prior to soldering. Selection of the flux will depend on the type of pc board and other components mounted on the board. Additionally, the flux must be compatible with the wave solder line, manufacturing, health, and safety requirements. Call the PRODUCT INFORMATION number at the bottom of page 1 for consideration of other types of flux. Flux types that are compatible with these switches are provided in Figure 5.

PROCESS STEP	CLEANING FLUX		
	ORGANIC	RA (Active) ROSIN	RMA (Mildly Active) ROSIN
1	Heat	Heat	Extra pre-clean
2	Solder	Solder	Heat
3	Wash in tap water or saponifier●	Wash with saponifier●	Solder
4	Rinse in tap or de-ionized water	Rinse in tap or de-ionized water	Wash in saponifier●
5	Dry in ambient air or radiant heater	Dry in ambient or radiant heater	Rinse in tap or de-ionized water
6	—	—	Dry in ambient air or radiant heater

- Reduces residue to soap.

Figure 5

B. Solder ing Process

Refer to Paragraph 2.5 for instructional material that is available for establishing soldering guidelines. The switches can be soldered using wave soldering or equivalent soldering techniques. It is recommended using SN60 or SN62 solder for these switches. The maximum solder profile temperature should be $245\pm 10^{\circ}\text{C}$ [$473\pm 10^{\circ}\text{F}$]. These switches are not recommended for reflow process.

C. Cleaning

After soldering, removal of fluxes, residues, and activators is necessary. Automatic in-line cleaning is recommended for the sealed switch. Installation in a socket is recommended for the unsealed switch. Consult with the supplier of the solder and flux for recommended cleaning solvents. Cleaners must be free of dissolved flux and other contaminants. It is recommended cleaning with the pc board on its edge. If using an aqueous cleaner, standard equipment such as a soak-tank or an automatic in-line machine should be used. The following is a list of common cleaning solvents that will not affect the switches for the time and temperature specified. See Figure 6.

NOTE



Vapor cleaning (with the pc board on edge) is preferred over submersion in a liquid cleaner. Unsealed switches should not be submerged due to contaminants in the cleaning bath.

CAUTION



Do NOT ultrasonically clean switches sealed with tape or masking material.

DANGER



Consideration must be given to toxicity and other safety requirements recommended by the solvent manufacturer. Refer to the manufacturer's Material Safety Data Sheet (MSDS) for characteristics and handling of cleaners. Trichloroethylene and Methylene Chloride is not recommended because of harmful occupational and environmental effects. Both are carcinogenic (cancer-causing).

NOTE



If you have a particular solvent that is not listed, contact PRODUCT INFORMATION at the number at the bottom of page 1.

CLEANER		TIME (Minutes)	TEMPERATURE (Maximum)
NAME	TYPE		
ALPHA 2110	Aqueous	1	100°C [212°F]
BIOACT EC-7	Solvent	5	
Butyl CARBITOL Solvent	Solvent	1	Ambient Room
Isopropyl Alcohol	Solvent	5	100°C [212°F]
KESTER 5778	Aqueous	5	
KESTER 5779	Aqueous	5	
LONCOTERGE 520	Aqueous	5	
LONCOTERGE 530	Aqueous	5	
Terpene Solvent	Solvent	5	

Figure 6

D. Drying

When drying cleaned unsealed assemblies and pc boards, make certain that the housing temperature does not exceed 130°C [270°F]. Excessive temperatures may cause housing degradation. When processing the economy sealant, make certain that the sealant temperature does not exceed 100°C [212°F] for 1 minute. This is a hot melt sealant and will reflow.

3.8. Checking Installed Switches

The solder tail must be through its intended hole in the pc board. Solder fillet must be evenly formed around each solder tail. The housing of the switch must be seated on the pc board not exceeding the dimension given in Figure 4.

3.9. Removal and Repair

Damaged or defective switches must NOT be used and should be replaced. The switches must be removed from the pc board by standard de-soldering methods.



When removing or replacing switches, care must be taken not to damage other pc board components during the de-soldering process.

4. QUALIFICATIONS

DIP programming switches are not required to be agency approved.

5. TOOLING

No tooling is required for manual placement of these switches; however, a pc board support that provides relief for protruding components must be used to prevent deformation of contact tails. The pc board support must be custom made. See Figure 7.

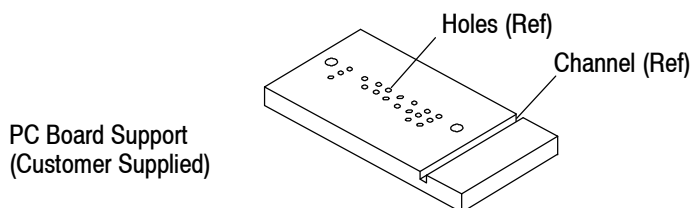


Figure 7

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6. VISUAL AID

Figure 8 shows a typical application of DIP programming switches. This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

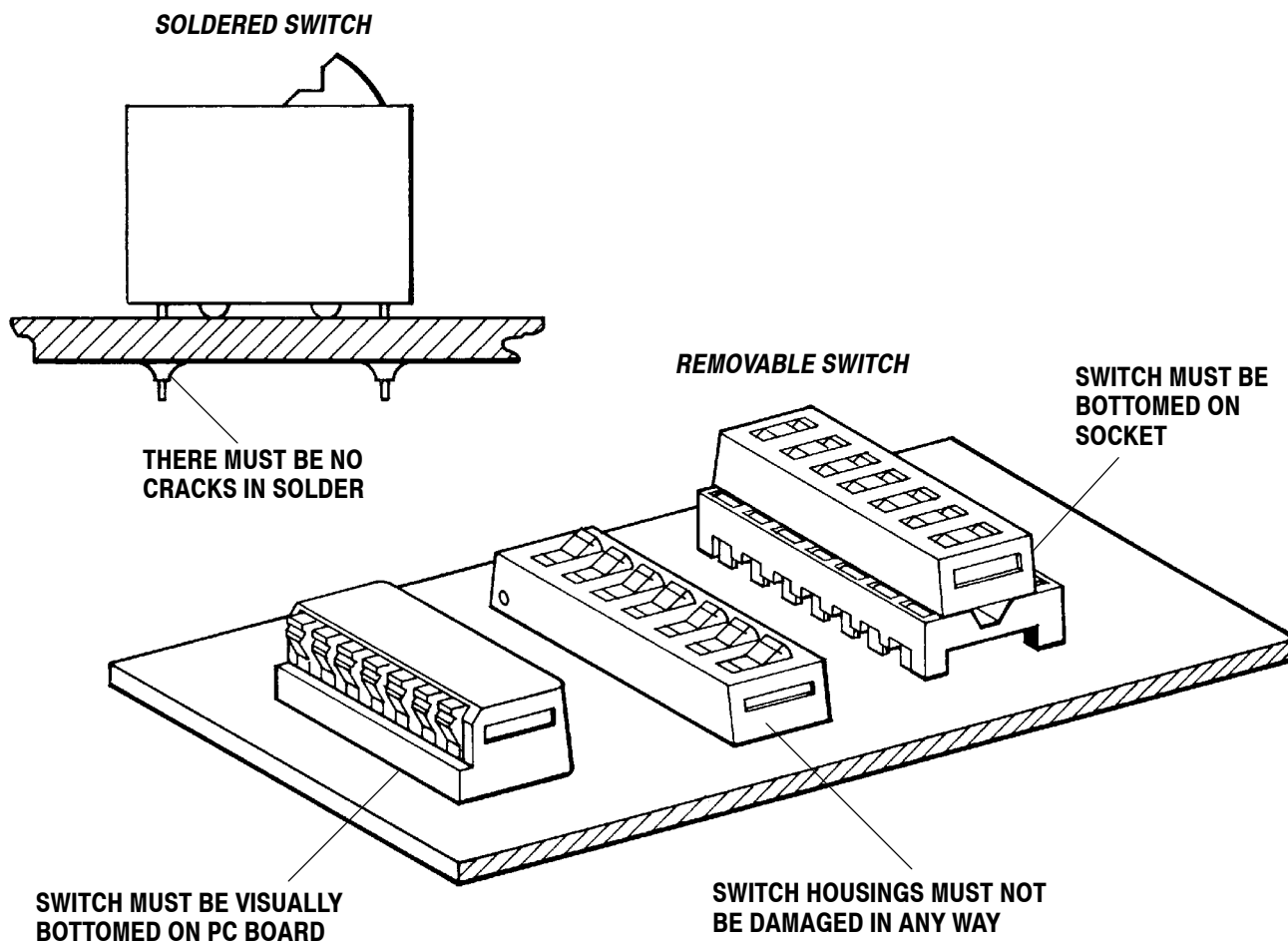


FIGURE 8. VISUAL AID

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Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9